
Call for Papers

Power Electronics Conference

From Materials to Systems - the latest innovations

14-15 November 2017 / Munich Germany
Co-located with productronica

Introduction

Since the turn of the century Power semiconductors have become increasingly important as enabler for state-of-the-art consumer applications, industrial systems and, increasingly so, transportation vehicles and automobiles. Several industries have shifted their development focus gradually towards power semiconductors to provide high efficiency power conversions and variable motor drives or related systems. Exciting new start-ups and spin-offs are crowding the emerging space created by novel power semiconductor (wide band-gap) materials and innovative packaging concepts and working diligently towards its successful introduction.

The excitement in our mature and quite risk-averse industry has recently peaked, when the paradigm of the theoretical Silicon performance limit was shattered by introduction of the CoolMos technology. Even more recently, the very reliable tram and train industry in Japan has started to integrate High-Voltage Silicon Carbide technology and, during the recent Google Little-box challenge a GaN Transistor topology revolutionized the power density of a solar inverter.

Every year the Semicon Power semiconductor conference provides the opportunity to hand selected experts in material, technology, marketing and application to review and present the progress in their related fields to their colleges and interested exhibition visitors. Our call for abstracts is now open for submission.

Topics

- Applications
 - Vehicle electrification
 - Transportation (tram, train, metro, busses, trucks)
 - Aerospace
 - Renewable energy generation and conversion
 - Energy storage, power transmission and distribution
 - Power electronics for oil & gas
 - Wide Band Gap devices in high-frequency applications

- Advanced Power Devices and Materials
 - Materials for power devices: Si, GaN, SiC and beyond
 - progress in Silicon power devices
 - progress in Wide Band Gap devices
 - progress on Si, SiC and GaN materials and processing

- Integration and packaging of power devices
 - Packaging solutions for vibrations, humid and high temperate environments
 - Thermal management aspect
 - high temperature packages
 - PCB embedding
 - low inductance packaging
 - Aspects of integration: materials and passives, device and system level solutions
- Test and reliability (methods & equipment)
 - Reliability testing
 - application testing
 - wafer level and final test screening methodologies
 - failure modes for Wide Band Gap devices
 - cosmic radiation hardness simulation and testing

Instructions to submit an abstract – To submit your abstract please click [here](#).

General guidelines:

- Please submit your abstracts, biography and a photo via internet until **28 April 2017**. Abstracts submitted via fax, e-mail, post, or other methods will generally not be accepted.
- The conference language is English.
- The abstract should have between 1.000 and 2.000 characters (Starting with descriptive paragraph identifying issue addressed and solution).
- Abstract changes and corrections will be accepted until the 28 April 2017.

Your presentation may not be included in the review process unless the information is complete.

Evaluation criteria include significance, usefulness for the manufacturing world and clarity and accuracy as a paper. Abstracts will be peer-reviewed and selected relative to the points above. We encourage application related presentations, i.e. on joint projects between users and suppliers. Papers are to be non-commercial and focus on the technical/economical merits of a process rather than the individual company's product benefits.

Deadline: **Submit your abstracts and biography until 28 April 2017.**

Changes: After your first registration your data are saved. Changes can be made any time until **28 April 2017**.

Notification: **Selected presenters will be notified by 17 July 2017.**

Power Electronics Program Committee:

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